## SN54HCT32, SN74HCT32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

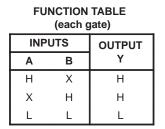
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- Inputs Are TTL-Voltage Compatible
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

The 'HCT32 contain four independent 2-input OR gates. They perform the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or Y = A + B in positive logic.

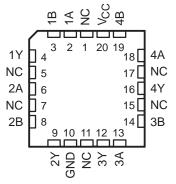
The SN54HCT32 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74HCT32 is characterized for operation from  $-40^{\circ}$ C to 85°C.





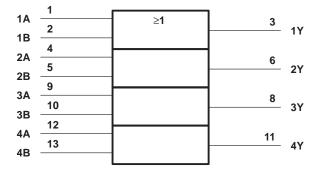
1A [ 1B [ 1Y [ 2A [ 2B [ 2Y [ GND ]	3 4 5 6	υ	12 11 10	] V <sub>CC</sub> ] 4B ] 4A ] 4Y ] 3B ] 3A ] 3Y

SN54HCT32 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, N, PW, and W packages.

### logic diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range<sup>†</sup>

Supply voltage range, $V_{CC}$ Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (se Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) Continuous current through $V_{CC}$ or GND Package thermal impedance, $\theta_{JA}$ (see Note 2):	ee Note 1) C) (see Note 1)	±20 mA ±20 mA ±25 mA ±50 mA 127°C/W 158°C/W
	PW package	170°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

#### recommended operating conditions

		SN54HCT32			SN74HCT32			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5	\$ 5.5	4.5	5	5.5	V
VIH	High-level input voltage	$V_{CC}$ = 4.5 V to 5.5 V	2	N.	12	2			V
VIL	Low-level input voltage	$V_{CC}$ = 4.5 V to 5.5 V	0	R	0.8	0		0.8	V
VI	Input voltage		0	1	VCC	0		VCC	V
VO	Output voltage		0	22	VCC	0		VCC	V
tt	Input transition (rise and fall) time		<u>0</u>	5	500	0		500	ns
Т <sub>А</sub>	Operating free-air temperature		-55		125	-40		85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vee	T <sub>A</sub> = 25°C			SN54HCT32		SN74HCT32		UNIT
PARAMETER	1231 CO	NDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Vou	VI = VIH or VIL	I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
Voh	VI = VIH OL VIL	I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.3		3.7		3.84		v
Ve		I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL	$V_{I} = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	V
l	VI = ACC  or  0		5.5 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	5.5 V			2	Ç,	40		20	μA
∆ICC‡	One input at 0.5 V Other inputs at 0 or		5.5 V		1.4	2.4	aogl	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10	Y	10		10	pF

<sup>‡</sup>This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.



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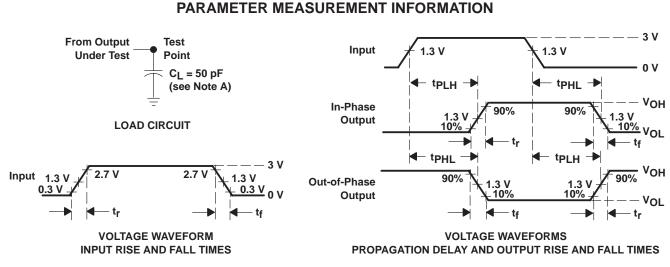
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# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	FROM TO		Τį	λ = 25°C	;	SN54HCT32	SN74HCT32	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT	
÷.	A or B	V	V	4.5 V		15	24	35	30	20
<sup>t</sup> pd	AUIB	T	5.5 V		13	22	32	27	ns	
	τ. V	4.5 V		9	15	22	19			
<sup>t</sup>		ŕ	5.5 V		8	14	20	17	ns	

### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	20	pF



- NOTES: A. CL includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 1. Load Circuit and Voltage Waveforms



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